

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	((("6390690") or ("6600853") or ("4465333") or ("6257771") or ("6623177") or ("20030128933") or ("20030219217")).PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:12
S2	0	("2003/0128933").URPN.	USPAT	OR	OFF	2004/11/30 12:03
S3	1972	(drill\$1 or drilling\$1) and (plate\$1 or plating\$1) and (etch or etching) and ((insulate\$1 or insulating\$1) same (epoxy or resin or adhesive))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:06
S4	71	S3 and (((electo or electric\$3) and (opto\$4 or optical)) with (via\$1 or hole\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:08
S5	88	S3 and (((electo or electric\$3) and (opto\$4 or optical)) with (via\$1 or hole\$1 or channel\$1 or path\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:08
S6	1522	S3 and (copper with (clad\$1 or cladding\$1 or laminate\$1 or layer\$1 or layering\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:10
S7	54	S6 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:10
S8	19	("3351816").URPN.	USPAT	OR	OFF	2004/11/30 12:11
S9	9	("RE27089").URPN.	USPAT	OR	OFF	2004/11/30 12:14
S10	70	("5282312").URPN.	USPAT	OR	OFF	2004/11/30 13:47
S11	19	("3351816").URPN.	USPAT	OR	OFF	2004/11/30 14:33
S12	9	("5386627").URPN.	USPAT	OR	OFF	2004/11/30 15:04
S13	27	("5421083").URPN.	USPAT	OR	OFF	2004/11/30 15:21
S14	0	("6787710").URPN.	USPAT	OR	OFF	2004/11/30 15:30
S15	3	("5421083" "5502893" "5949030").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/30 15:30

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S17	33	("4642889" "4675788" "4776087" "5233133" "5323534" "5363550").PN. OR ("5421083").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/30 15:32
S18	47	(US-20030128933-\$ or US-20010010250-\$ or US-20020016018-\$ or US-20030129383-\$ or US-20030178229-\$ or US-20040109628-\$ or US-20040109627-\$ or US-20040120631-\$ or US-20040145873-\$ or US-20040148766-\$ or US-20040212030-\$).did. or (US-4153988-\$ or US-5282312-\$ or US-5386627-\$ or US-5570504-\$ or US-5640761-\$ or US-5719354-\$ or US-5906043-\$ or US-5906042-\$ or US-5962815-\$ or US-6016005-\$ or US-6190509-\$ or US-6242286-\$ or US-6499214-\$ or US-6518091-\$ or US-6800537-\$ or US-6820330-\$ or US-5421083-\$ or US-6438281-\$ or US-6448506-\$ or US-6564454-\$ or US-6629362-\$ or US-6664127-\$ or US-5568682-\$ or US-5729897-\$ or US-5744285-\$ or US-5707893-\$).did. or (US-5949030-\$ or US-6020049-\$ or US-6195883-\$ or US-6303881-\$ or US-6787710-\$ or US-5502893-\$ or US-5224265-\$ or US-5232548-\$).did. or (US-3351816-\$ or US-RE27089-\$). did.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/30 15:44
S19	21	S18 and (fiber\$1 or wave\$guide\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 15:44

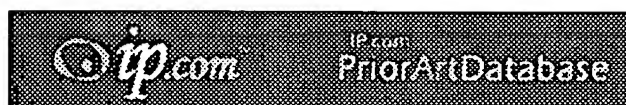
S20	127493	(optical or opto) with (via\$1 or hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
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S22	198	S21 and ((insulation or insulating or resin) with adhesive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:03
S23	187	S22 not S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:03
S24	171	S23 not (S4 or S5 or S7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:09
S25	43	S24 and ((optical with fiber\$1) or wave\$guide\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:09
S26	864	S20 and 385/14.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
S27	49	S21 and 385/14.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16

S28	49	(US-20010010250-\$ or US-20020016018-\$ or US-20030128907-\$ or US-20030128933-\$ or US-20030129383-\$ or US-20030178229-\$ or US-20040001661-\$ or US-20040109627-\$ or US-20040109628-\$ or US-20040120631-\$ or US-20040145873-\$ or US-20040148766-\$ or US-20040212030-\$).did. or (US-4153988-\$ or US-5224265-\$ or US-5232548-\$ or US-5282312-\$ or US-5386627-\$ or US-5421083-\$ or US-5502893-\$ or US-5568682-\$ or US-5570504-\$ or US-5640761-\$ or US-5707893-\$ or US-5719354-\$ or US-5729897-\$ or US-5744285-\$ or US-5906042-\$ or US-5906043-\$ or US-5949030-\$ or US-5962815-\$ or US-6016005-\$ or US-6020049-\$ or US-6190509-\$ or US-6195883-\$ or US-6242286-\$ or US-6303881-\$ or US-6438281-\$ or US-6448506-\$).did. or (US-6499214-\$ or US-6518091-\$ or US-6564454-\$ or US-6629362-\$ or US-6664127-\$ or US-6787710-\$ or US-6800537-\$ or US-6820330-\$).did. or (US-3351816-\$ or US-RE27089-\$). did.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/12/01 12:28
S29	8	S28 and ((epoxy or resin or adhesive) same (light))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:38
S30	13	S28 and prepreg	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:39
S31	2	S28 and prepreg and ((optical with fiber\$1) or wave\$guide\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:39
S32	1	((("6839476") or ("6879423")).PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:13

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S36	393	(opto\$via or (optical with via) or via\$hole or (via with hole)) and (copper with laminate) and (resin with adhesive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/12 09:24
S37	14	("3546009").URPN.	USPAT	OR	ON	2005/04/12 09:28
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S46	26	("4854038" "5120384" "5153986" "5153987" "5185502" "5191174" "5224265" "5232548" "5298685" "5316787" "5362534" "5421083" "5435057" "5557843" "5558928" "5685070" "5745333" "5747222" "5822856" "5834160" "6103135" "6131279" "6181004" "6201194" "6215372" "6255039").PN. OR ("6832436").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 10:13
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April 12, 2005

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Result # 1 Relevance: ○○○○○○

**PREVIEW**
this document**Via Punching Device for Multi-Layered Ceramic Substrates**

29-Jan-2005

IPCOM000037316D

English

A technique is described whereby the mechanical punching of vias in multi-layered ceramic substrates is controlled through the use of independently controlled punching stations. The new via punching device is an improvement of a previous system which uses only a ...

Result # 2 Relevance: ○○○○○○

**PREVIEW**
this document**Minimal Metal Mask for Reactive Ion Etching Polyimide**

13-Feb-2005

IPCOM000055528D

English

The fabrication of thin film modules of multi-layered ceramic multichip packaging chips requires the making of via holes through a thermally cured resin which serves as a dielectric between transmission line level and transmission line-ground plane levels.

Result # 3 Relevance: ○○○○○○

**PREVIEW**
this document**SIP: Session Initiation Protocol (RFC3261)**

09-Aug-2002

IPCOM000009156D

English

This document describes Session Initiation Protocol (SIP), an application layer control (signaling) protocol for creating, modifying, and terminating sessions with one or more participants. These sessions include Internet telephony, multimedia distribution, and ...

Result # 4 Relevance: ○○○○○○

**PREVIEW**
this document**RETENTION OF PHOSPHORUS IN SILICON BENEATH SILICIDE CONTACTS DURING HIGH TEMPERATURE PROCESSING**

19-Oct-2001

IPCOM000005621D

English

After metal contacts and short-range interconnects are deposited on a substrate, there is often the need to carry out processing at high temperatures. This processing can cause phosphorus compound formation, grain size enhancement, contact improvement, and glass reflow for tapering of via holes in thick doped ...

Result # 5 Relevance: ○○○○○○

**PREVIEW**
this document**Manufacturing process to fabricate co-planar multi-layered printed circuit boards**

20-Jun-2003

IPCOM000014863D

English

A manufacturing process for insuring co-planarity of epoxy printed circuit boards fabricated with more than one level on a side having different surface dimensions is described. Individual layers of printed circuit material (comprised of differing circuit layout) are ...

Result # 6 Relevance: ○○○○○○

**PREVIEW**
this document**Method for Forming Wiring Patterns and Vias on a Substrate**

29-Jan-2005

IPCOM000036834D

English

This article describes a new method of defining wiring patterns and vias on a substrate.

pure metals or metallic alloys on various ceramic greensheets, fired ceramic substrates, or polymer surfaces. The disclosed process capability for obtaining higher resolution ...

Result # 7 Relevance: 



PREVIEW
Full Document

Method for Structural Characterization of Bi-Layer for Use in Personal Care Products via Microscopy Analysis

14-Dec-2004

IPCOM000033526D

English

A methodology has been developed to characterize the structural multi-layer absorbent materials. The method is able to detect a z-distribution of polypropylene and cellulose components. Output method was used to determine that the ...

Result # 8 Relevance: 



PREVIEW
Full Document

Single-Crystal Silicon Embedded With Insulated Co Wires

28-Jan-2005

IPCOM000036028D

English

In packaging technology, a generic problem is that the packages tend to have a different thermal expansion coefficient from that of the substrate. Consequently, upon thermal cycling during operation a shear stress is applied on those solder balls that join the chip and ...

Result # 9 Relevance: 



PREVIEW
Full Document

Network File System (NFS) version 4 Protocol (RFC1755)

30-Apr-2003

IPCOM000012311D

English

The Network File System (NFS) version 4 is a distributed file system which owes heritage to NFS protocol version 2, RFC 1094, and RFC 1813. Unlike earlier versions, the NFS version 4 protocol supports file access while integrating support for ...

Result # 10 Relevance: 



PREVIEW
Full Document

Towards Requirements for IP Routers (RFC1716)

12-Sep-2000

IPCOM000003963D

English

The goal of this work is to replace RFC-1009, Requirements for Gateways ([INTRO:1]) with a new document.

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April 12, 2005

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Result # 11 Relevance: ○○○○○

**PREVIEW**
this document**Silver halide photographic light-sensitive material super-rapid processing**

12-Sep-2000

IPCOM000000670D

English

A silver halide photographic light-sensitive material comprising having the first photographic structural layer comprising one or a side of the support and the second photographic structural layer one or more layers on the other side of ...

Result # 12 Relevance: ○○○○○

**PREVIEW**
this document**Exhalation duct**

12-Sep-2000

IPCOM000000800D

English

An exhalation duct is formed from a gas impermeable covering material extending through the length of the duct to define a cylindrical opening. A lower end of the duct is formed with a plurality of exhalation holes or openings in the covering ...

Result # 13 Relevance: ○○○○○

**PREVIEW**
this document**Efficient Two Layered Organic Photovoltaic Device**

03-Mar-2005

IPCOM000085960D

English

For organic light-absorbing species at a solid-solid interface, efficient photoactivated free-carrier generation has so far been limited by the requirement of very high quality materials (silver halide photography) or by the requirement of very high quality materials (electrophotography). Yet the solar ...

Result # 14 Relevance: ○○○○○

**PREVIEW**
this document**NFS version 4 Protocol (RFC3010)**

17-Aug-2001

IPCOM000005202D

English

NFS (Network File System) version 4 is a distributed file system that owes heritage to NFS protocol versions 2 [RFC1094] and 3 [RFC1813]. Earlier versions, the NFS version 4 protocol supports traditional file sharing while integrating support for file ...

Result # 15 Relevance: ○○○○○

**PREVIEW**
this document**Requirements for Internet gateways - draft (RFC0959)**

13-Jul-2001

IPCOM000004983D

English

The following sections are intended as an introduction and background for those unfamiliar with the DARPA Internet architecture and the Internet gateway model. General background and discussion on the Internet architecture and supporting protocol suite can be found in ...

Result # 16 Relevance: ○○○○○

**PREVIEW**
this document**Cylindrical keyed coupling for composite propulsion**

12-Sep-2000

IPCOM000001626D

English

A coupling for a torsional drive includes a rotatable shaft, an outer housing which has a keyway comprising a half-round groove. A rotatable coupling around the shaft and coaxial with the shaft has an inner surface

a second keyway, the second keyway also ...

Result # 17 Relevance: 



PREVIEW
this document

Softshell protective mask

12-Sep-2000

IPCOM000001350D

English

Form-fitting, comfortable, soft-shell protective apparel, common mask, for protecting the head, upper body and respiratory tract chemical/biological agents and toxins and radioactive particles. easy-to-put-on, heat and moisture-dissipating ...

Result # 18 Relevance: 



PREVIEW
this document

Advice for Internet Subnetwork Designers AUTHO (RFC3819)

09-Jul-2004

IPCOM000029724D

English

This document provides advice to the designers of digital communication equipment, link-layer protocols, and packet-switched local networks (collectively referred to as subnetworks), who wish to support transport protocols but may be unfamiliar with the Internet ...

Result # 19 Relevance: 



PREVIEW
this document

Method for high-density semiconductor packages and substrates fabricated on continuous reels

16-Jun-2004

IPCOM000029161D

English

Disclosed is a method for high-density semiconductor packages and substrates fabricated on continuous reels. Benefits include improved functionality, improved performance, improved reliability, and improved

Result # 20 Relevance: 



PREVIEW
this document

Requirements for IP Version 4 Routers (RFC1812)

13-Sep-2000

IPCOM000004069D

English

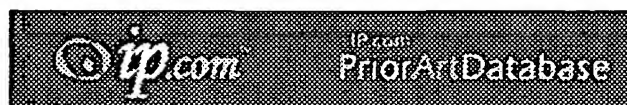
This memo replaces RFC 1716, "Requirements for Internet Gateways" ([INTRO:1]).

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Result # 21 Relevance:

**PREVIEW**
this document**Transparent Content Negotiation in HTTP (RFC2291)**

13-Sep-2000

IPCOM000002858D

English

HTTP allows web site authors to put multiple versions of the same document under a single URL. Transparent content negotiation is an extension of the HTTP negotiation mechanism, layered on top of HTTP, for automatically selecting the best version when the URL is accessed. This ...

Result # 22 Relevance:

**PREVIEW**
this document**Split barrel insulation displacing connector**

11-Sep-2000

IPCOM000000001D

English

A split-barrel connector terminal is presented wherein a wire connector terminal is released as a new wire is being connected. This feature is achieved by an aperture (13) located at a predetermined distance from the wire slot (12). When insertion tool (51) ...

Result # 23 Relevance:

**PREVIEW**
this document**Some Internet Architectural Guidelines and Philosophies (RFC3439)**

11-Dec-2002

IPCOM000010524D

English

This document extends RFC 1958 by outlining some of the philosophical guidelines to which architects and designers of Internet backbone networks should adhere. We describe the Simplicity Principle, which states that complexity is the primary mechanism that impedes ...

Result # 24 Relevance:

**PREVIEW**
this document**Requirements for Internet gateways (RFC1009)**

12-Sep-2000

IPCOM000001812D

English

The following material is intended as an introduction and background for those unfamiliar with the Internet architecture and the Internet gateway. General background and discussion on the Internet architecture and the supporting protocol suite can be found in the DDN ...

Result # 25 Relevance:

**PREVIEW**
this document**Performance Enhancing Proxies Intended to Mitigate Particular TCP Related Degradations (RFC3135)**

21-Aug-2001

IPCOM000005319D

English

This document is a survey of Performance Enhancing Proxies (PEPs) employed to improve degraded TCP performance caused by characteristics of specific link environments, for example, in satellite, wireless WAN, and wireless LAN environments. Different types of ...

Result # 26 Relevance:

**PREVIEW**
this document**SDP: Session Description Protocol (RFC2327)**

13-Sep-2000

IPCOM000002894D

English

This document defines the Session Description Protocol, SDP. SDP is used for describing multimedia sessions for the purposes of session announcement, session initiation, and session management.

session invitation, and other forms of multimedia session initiat

Result # 27 Relevance: 



PREVIEW
this document

Report of IAB Workshop on Security in the Internet Architecture - February 8-10, 1994 (RFC1636)

12-Sep-2000

IPCOM000002472D

English

This document is a report on an Internet architecture workshop the IAB and held at USC Information Sciences Institute on February 1994. This workshop generally focused on security issues in the architecture.

Result # 28 Relevance: 



PREVIEW
this document

Use of IPsec Transport Mode for Dynamic Routing

25-Sep-2004

IPCOM000031435D

English

IPsec can secure the links of a multihop network to protect communication between trusted components, e.g., for a secure virtual network or virtual private network (VPN). Virtual links established by IPsec can conflict with routing and forwarding ...

Result # 29 Relevance: 



PREVIEW
this document

Loader Debugger Protocol (RFC0909)

13-Sep-2000

IPCOM000003959D

English

Result # 30 Relevance: 



PREVIEW
this document

Heterojunction D.sup.- (or A.sup.+) millimeter and submillimeter wave detector

12-Sep-2000

IPCOM000000095D

English

A solid state detector for use in detecting submillimeter and millimeter radiation. The solid state detector comprises a semiconductor structure having alternating thin epitaxial layers of GaAs and AlGaAs doped with alternating conductivity type. Because ...

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